

Forward-looking Statement

- Information included in this presentation that are not historical in nature are "forward looking statements". C Sun cautions readers that forward looking statements are based on C Sun's reasonable knowledge and current expectations and are subject to various risks and uncertainties.
- Actual results may differ materially from those contained in such forward looking statements for a variety of reasons including without limitation, risks associated with demand and supply change, manufacturing and supply capacity, design win, time to market, market competition, industrial cyclicity, customer's financial condition, exchange rate fluctuation, legal actions, amendments of the laws and regulations, global economy change, natural disasters, and other unexpected events which may disrupt C Sun's business and operations.
- Accordingly, readers should not place reliance on any forward looking statements. Except as required by law, C Sun undertakes no obligation to update any forward looking statement, whether as a result of new information, future events, or otherwise.



志聖工業



QIC CEO Week 114.4.15



經營理念
皆大歡喜

G2C+

合力共創 同行致遠



善意的動機 引領事業走向成功

不論是在開創事業，或是在挑戰新任務時，我會先思考：
這是不是對世人有利？是不是利他的行為？

凡是能確信是基於利他、發自「善意動機」的事業，
最後無一例外，都能獲得好結果。

--- 摘自《心》稻盛和夫 ---

聯盟總人數：1700+



R&D 人數：560+

R&D佔聯盟總人數比例達 32.5%



1966年

1978年

1978年

***c sun* 志聖**

Thermal (熱)
Bonder (壓合)
Lamination (貼膜)
Peeling (撕膜)
UV/Plasma (光/電漿)

GPM 均豪精密

AOI (檢測)
Metrology (量測)
Grinding (研磨)
Polishing (拋光)

GMM 均華精密

Die Attach (黏晶)
Chip Sorter (揀晶)
Auto Jig Saw (切單挑揀)

聯盟核心技術

晶圓大廠
向下整合

Foundry + Advanced Packaging + Testing
(InFo、CoWoS、SoIC)



先進封裝
Advanced Packaging



Flip Chip > Fan out > 2.5D/3D + Testing
(SiP、PoP、McM、FoCoS)

OSAT
向上發展

c sun Bonder
Lamination
Peeling

GPM AOI
Metrology
Grinding
Polishing

GMM Die Attach
Chip Storter
Auto Jid Saw



c sun GPM

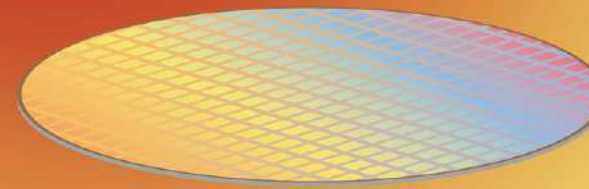
晶圓代工
再生晶圓

先進封裝

IC Substrate 、 HBM Packaging 、 2.5/3DIC



GT2C+
T STRATEGY ALLIANCE



人工智慧AI晶片市場規模 2023~2034 (單位: 美金10億)



臺灣西部黃金走廊：AI 晶片

先進封裝製程的閃亮鑽石鏈

臺灣在封裝測試市場的價值
佔有率

58.6 %

臺灣在晶圓製造市場的價
值佔有率

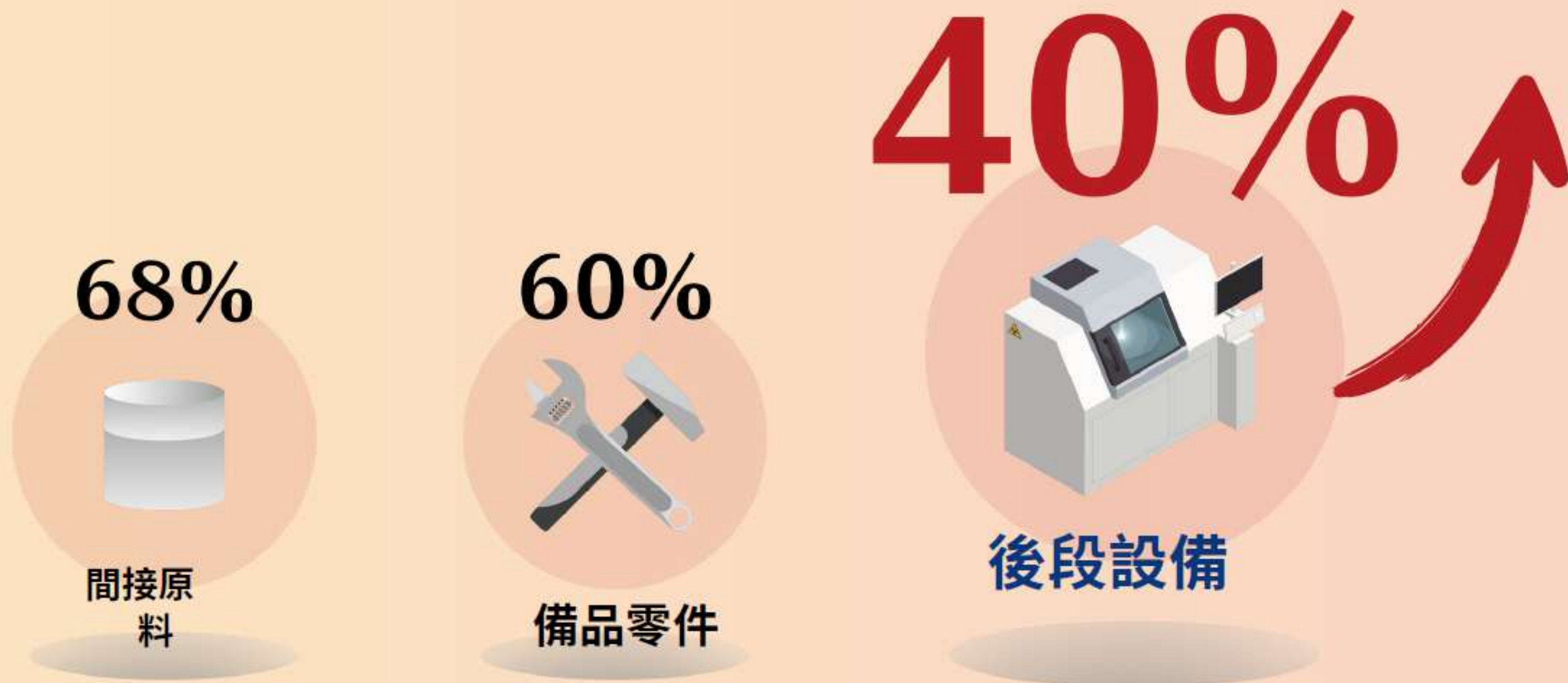
76.8 %



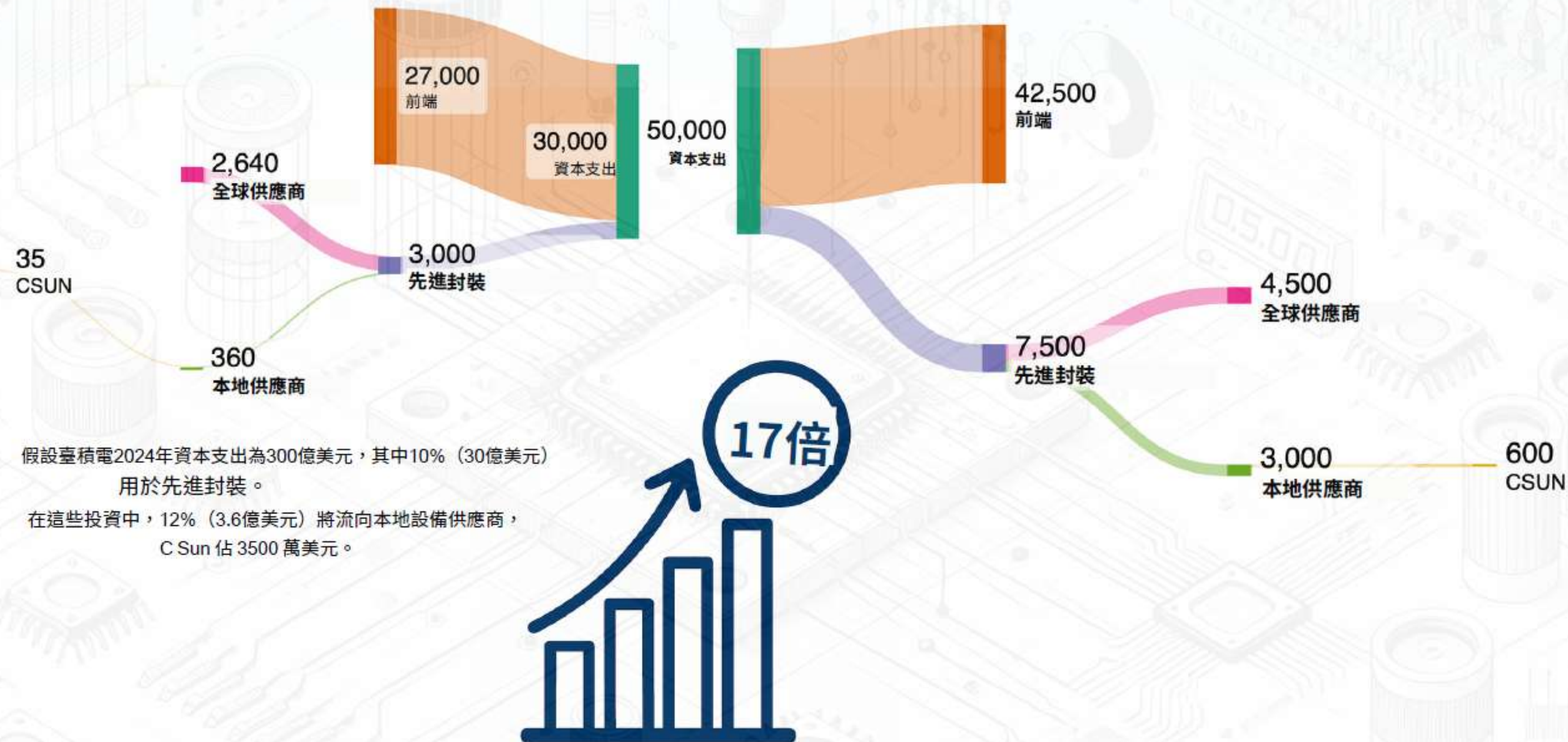
c sun

臺積電致力於提高本地採購比例

2030年願景展望



US\$M



假設臺積電2024年資本支出為300億美元，其中10%（30億美元）用於先進封裝。

在這些投資中，12%（3.6億美元）將流向本地設備供應商，C Sun 佔 3500 萬美元。

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公司簡介



2023、2024
TSMC Award

員工與家族
持股>40%

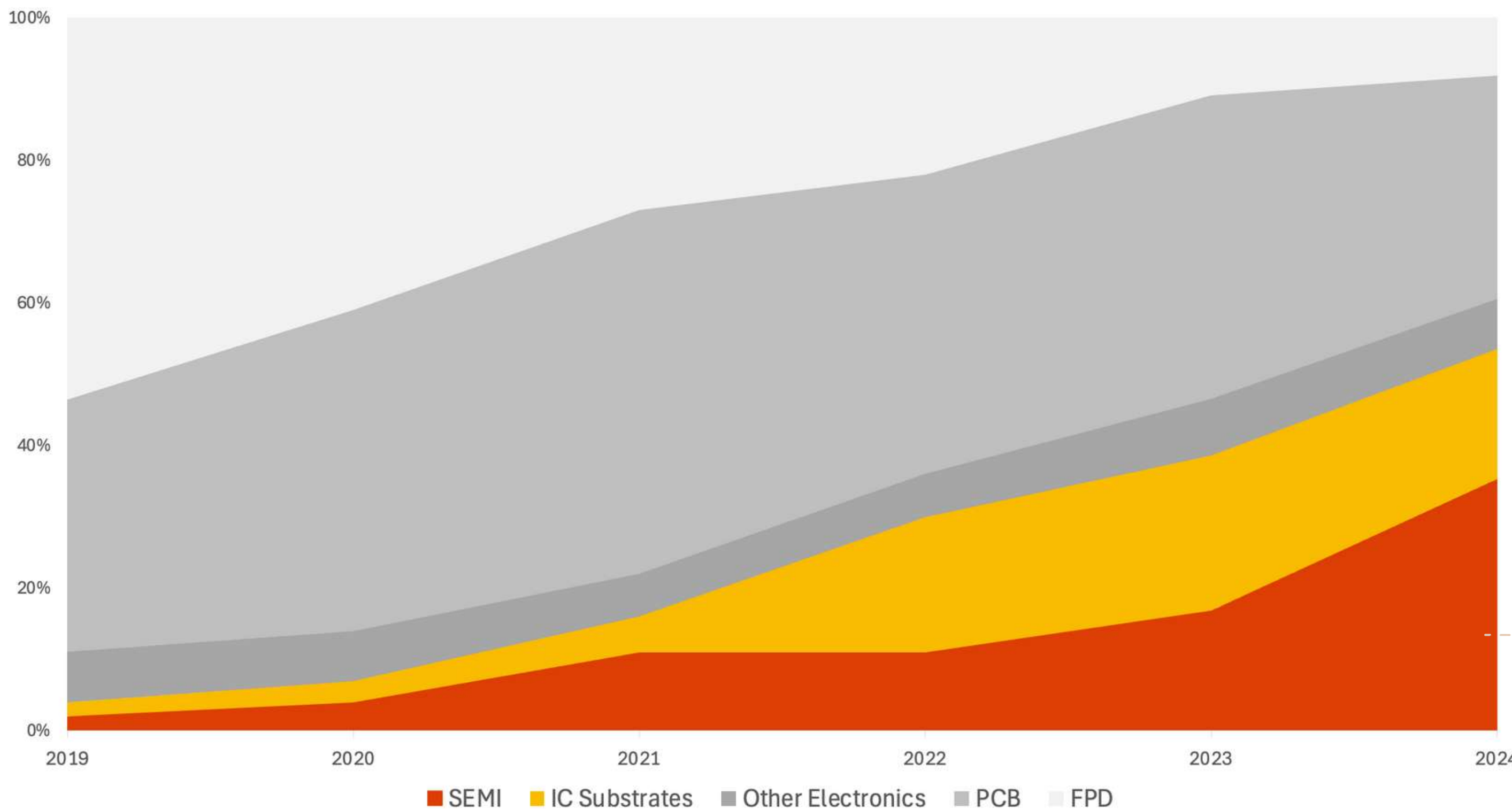


1966.9.28 創立
資本額:15.6億
董事長:梁茂生
總經理:梁又文

財務回顧

綜合損益表項目 (除另予註明者外，金額為新台幣百萬元)	2025 Q1	2024	2023	YoY 同比
營業收入淨額	1,309	4,818	3,626	32.9%
營業毛利率%		41.2%	41.5%	-0.3ppts
營業費用		(1,347)	(1,104)	22%
營業費用率%		28.0%	30.4%	-2.4ppts
營業利益率%		13.2%	11.1%	+2.1ppts
營業外收入與支出		344	181	90%
歸屬予母公司業主之本期淨利		719	486	48%
純益率%		14.9%	13.4%	+1.5ppts
每股盈餘(新台幣元)		4.8	3.12	54%
股東權益報酬率%		16.60%	14.11%	-

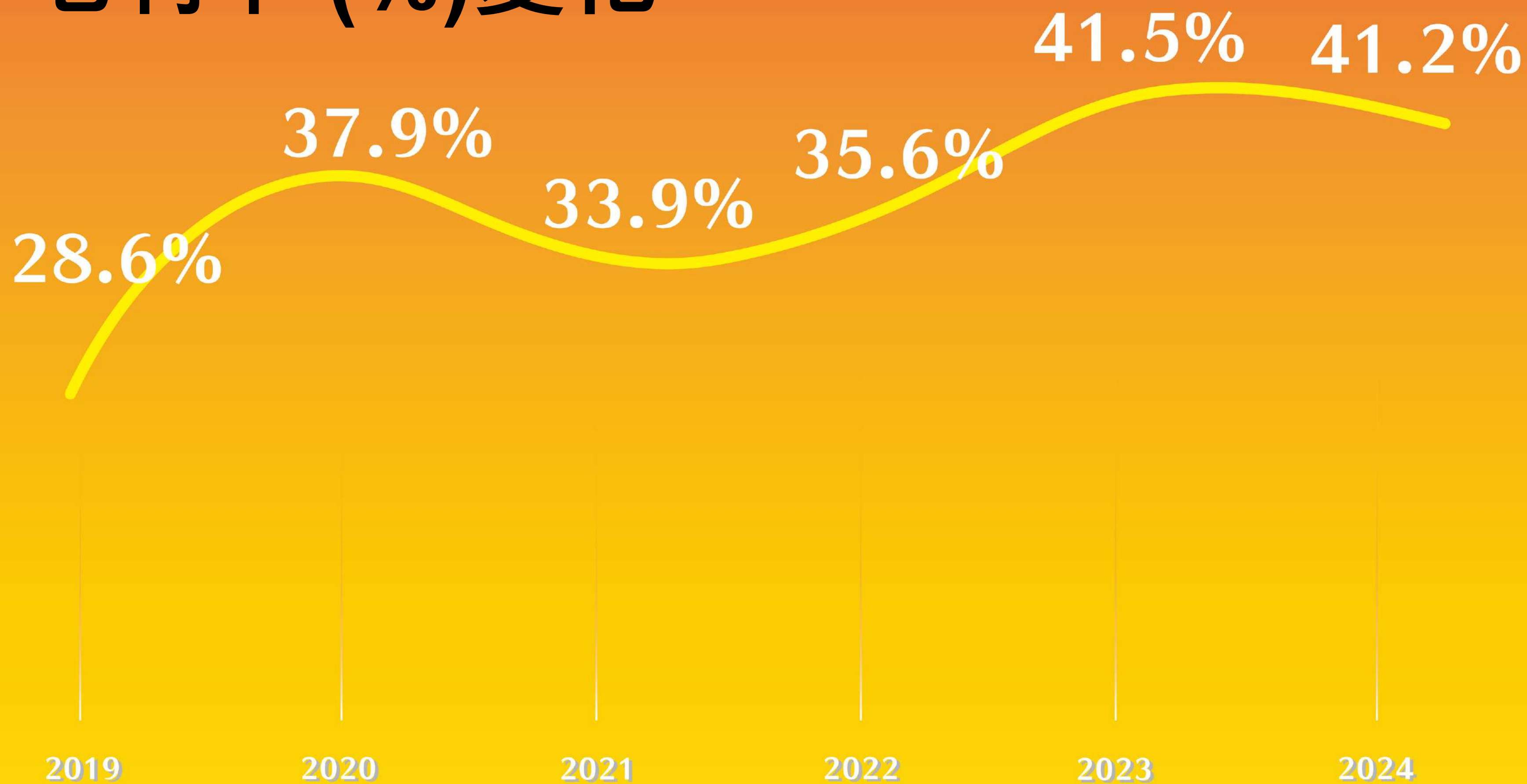
營收結構



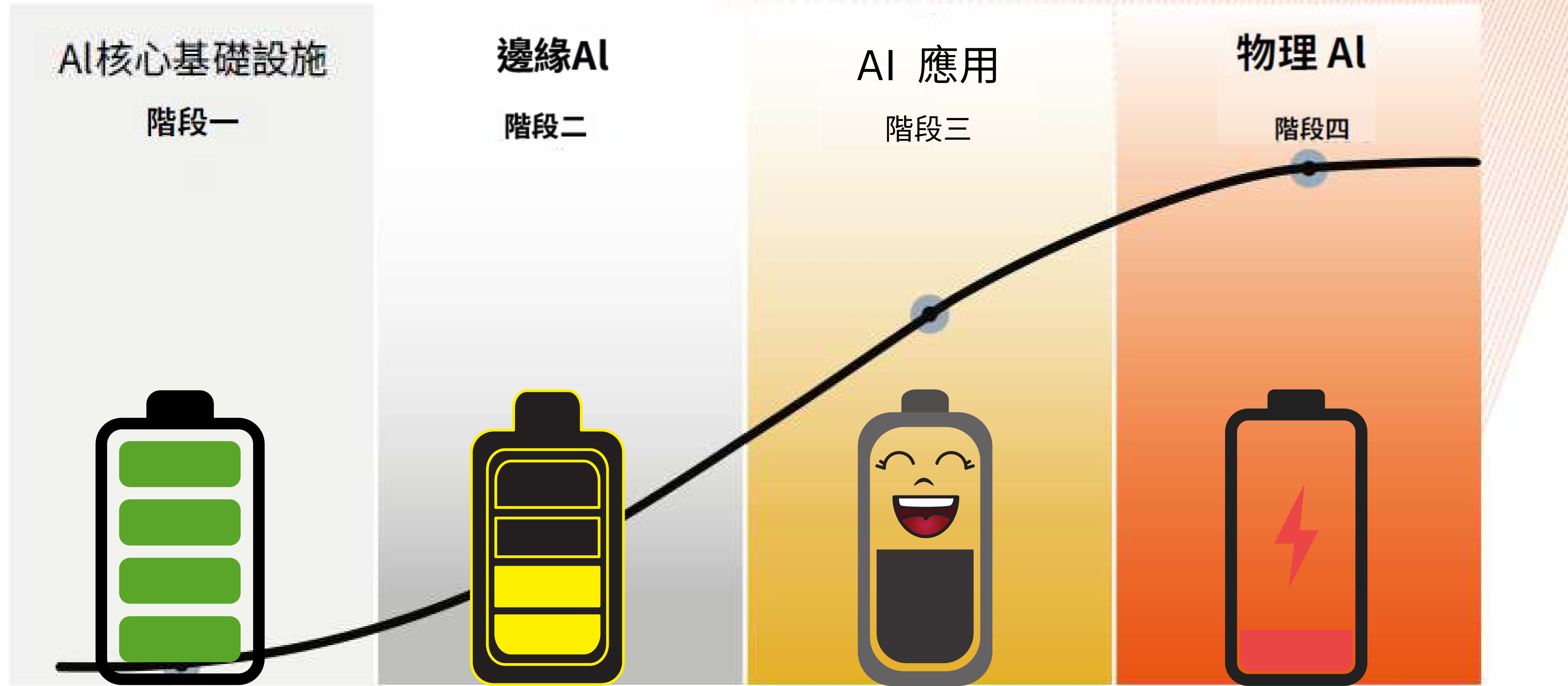
SEMI~35%



毛利率 (%)變化



Coatue的AI S曲線框架



AI 聚焦

HBM

oS

LPO

Assembly

IC Substrate

CoW

SoC/SolC

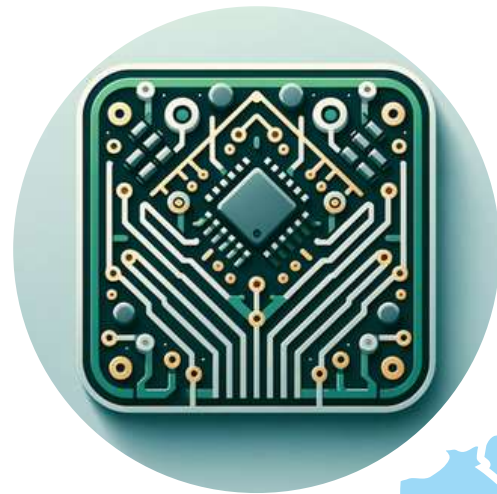
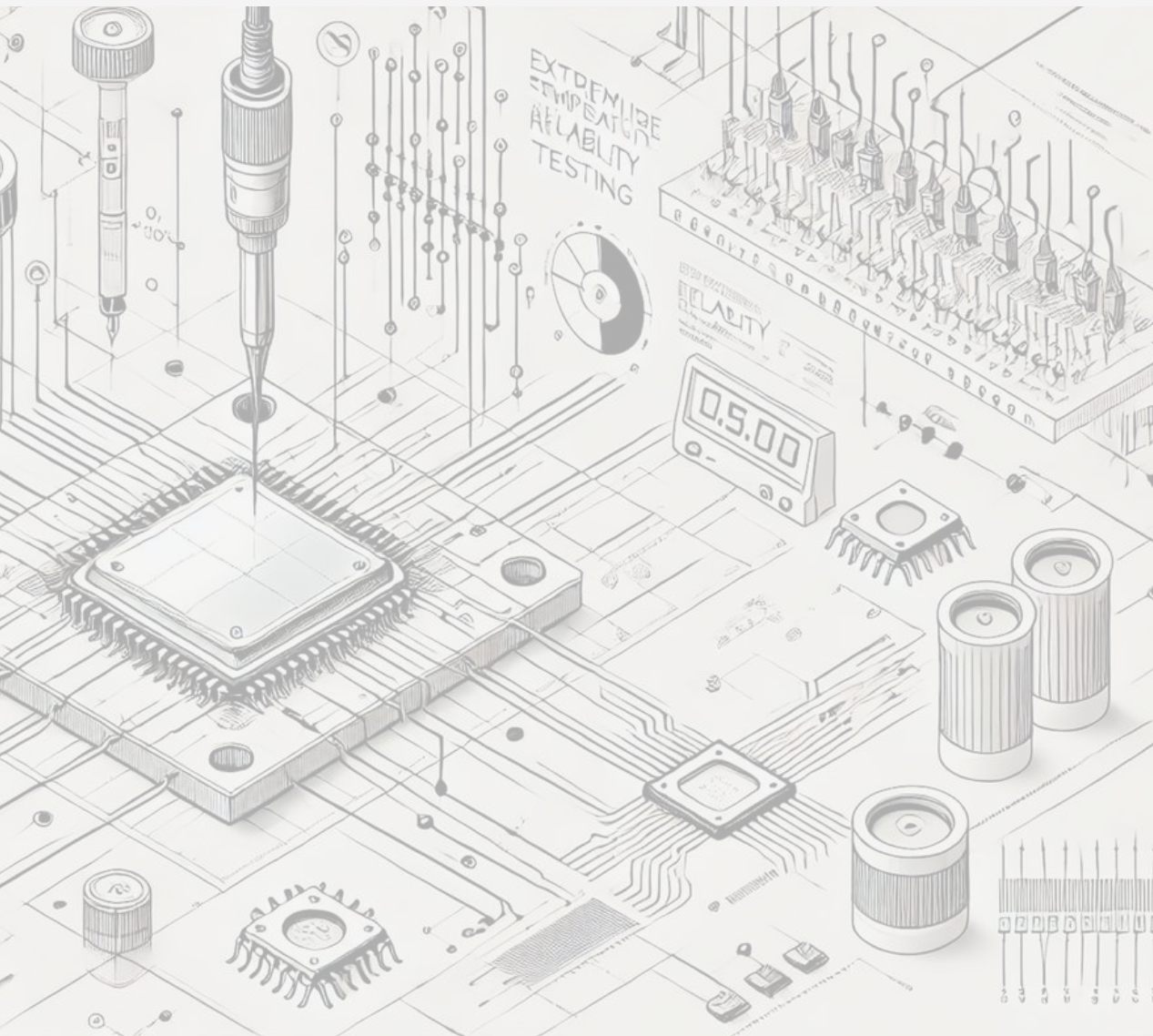
CPO

Test

Mother Board

2024

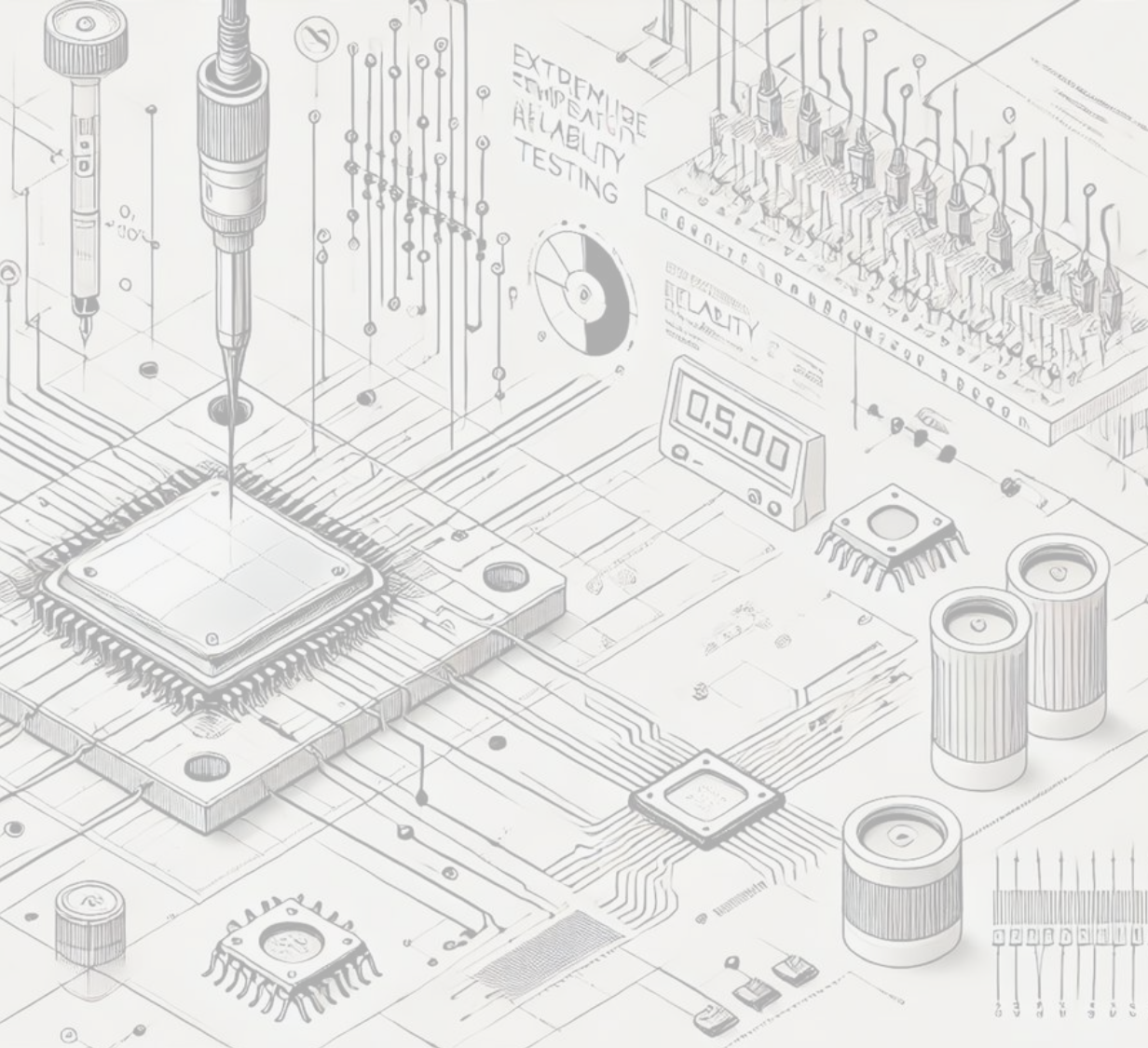
>50%



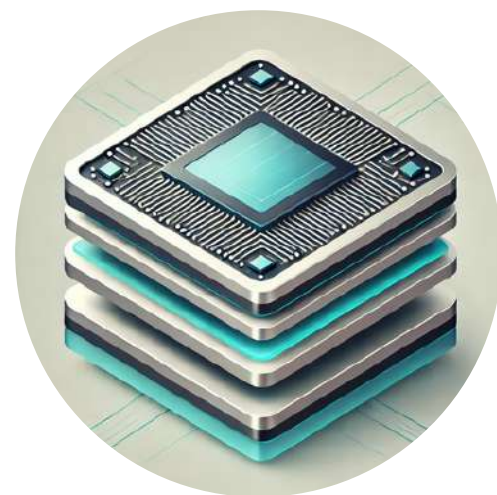
- AI伺服器與高密度互連板（HDI）需求回升
- 東南亞市場擴張
- 推動泰國印刷電路板（PCB）產業成長
- 台灣PCB廠商設備升級
- PCB在AI產業鏈中的演進



PCB產業
持續變革

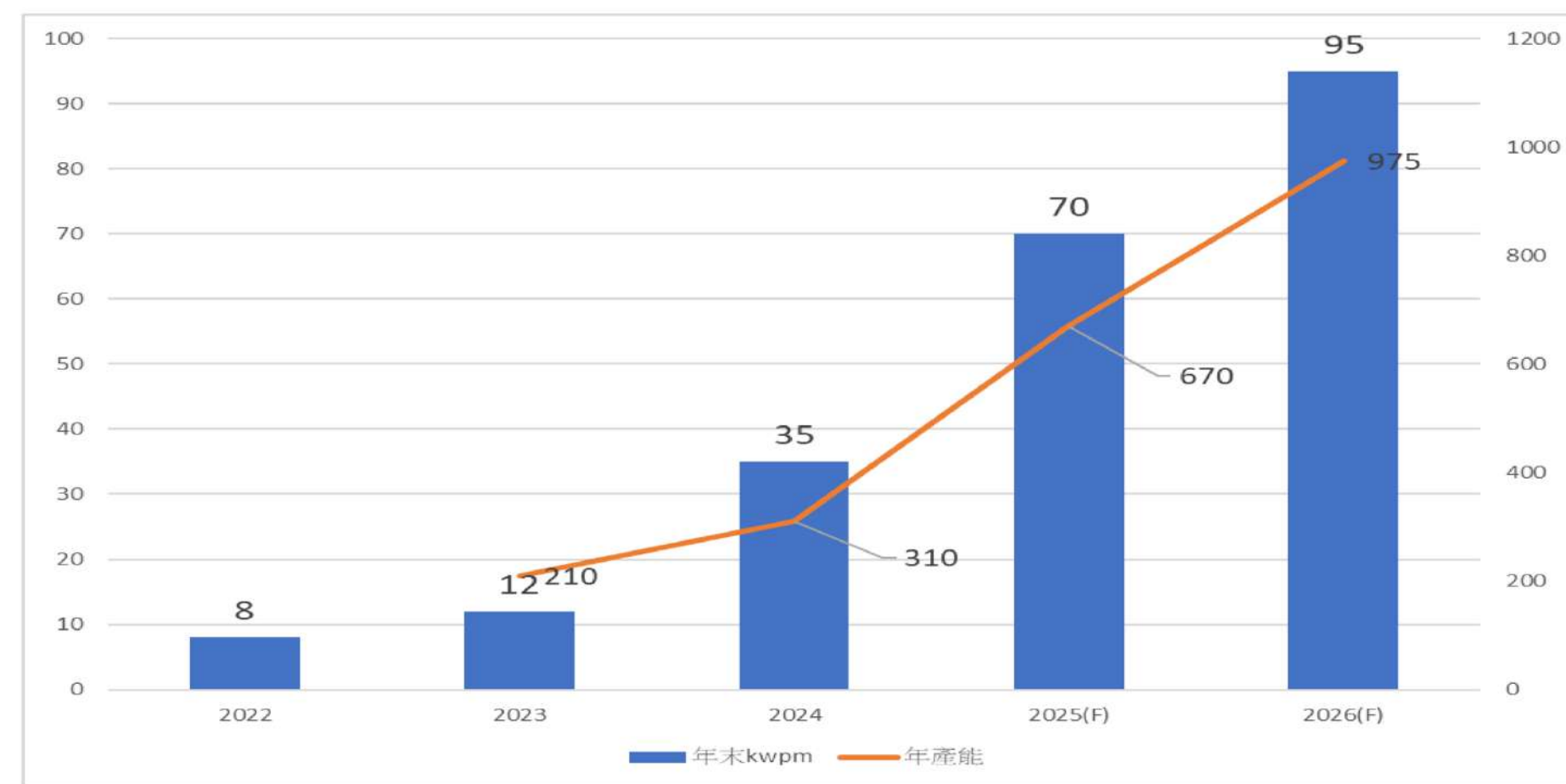


設備用於龍頭 客戶先進封裝 製程前景



CoWoS 製程與產能動態

- DeepSeek現象將鼓勵更多AI Logic IC 崛起，探索更多商機可能。
- CoWoS製程當前仍為AI晶片主要製程。
- 龍頭客戶產能擴張帶動設備需求，區塊業績成長可期。
- 關注 OSAT 廠商擴廠進程與增加新站點，提升志聖在客戶端整體滲透率。



資料來源：兆豐國際投顧預估



封測廠OSATs的收入佔比增長

世界前10大封測廠OSATs均為G2C+的客戶

4%  10%



ASE

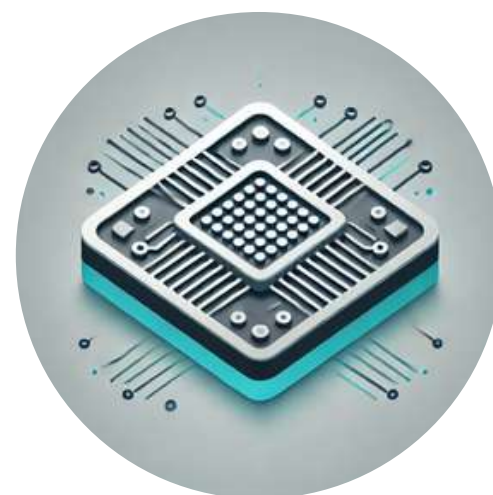
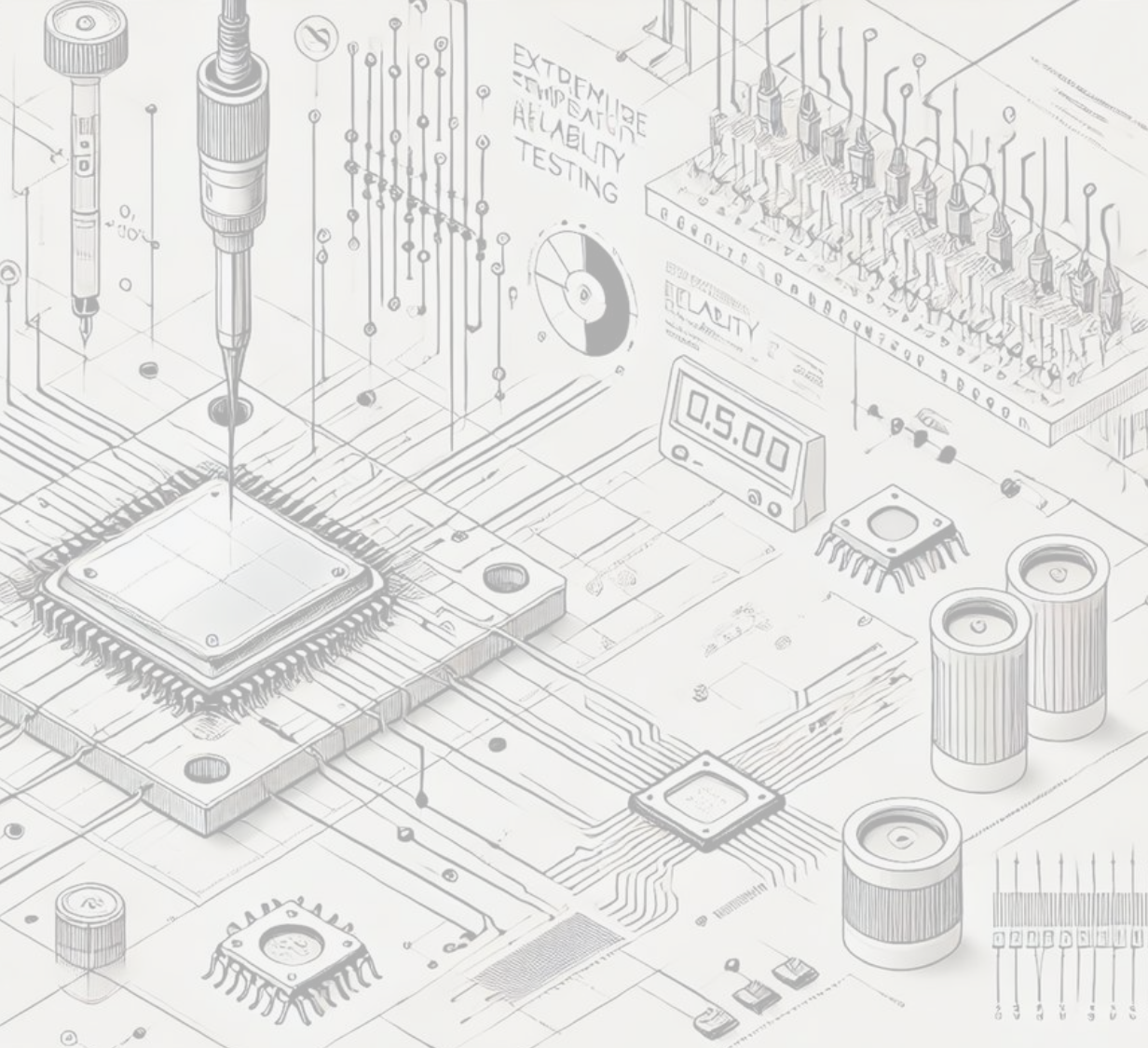


JCET

TF 通富微電



CHIPBOND
順邦科技



FoPLP 製程與發展動態

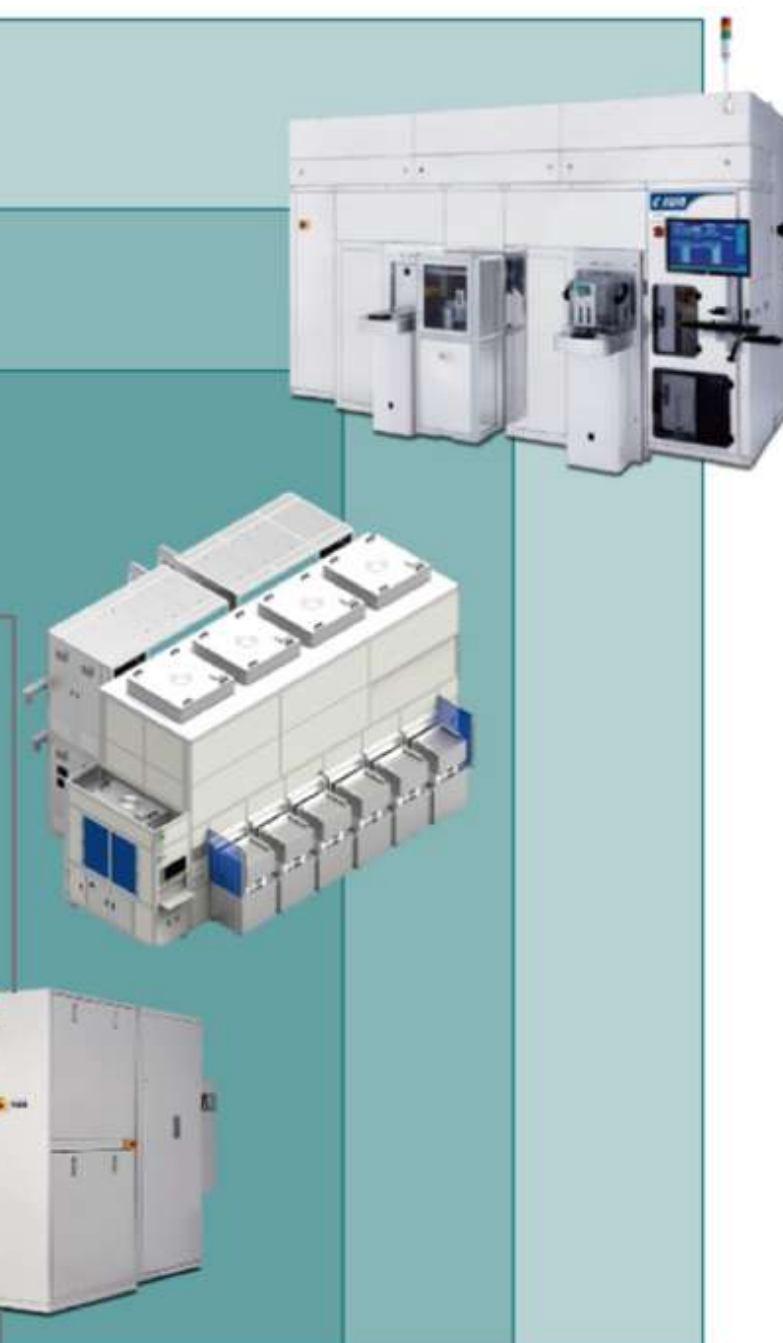
700 x 700

600 x 600

510 x 515

310 x 310

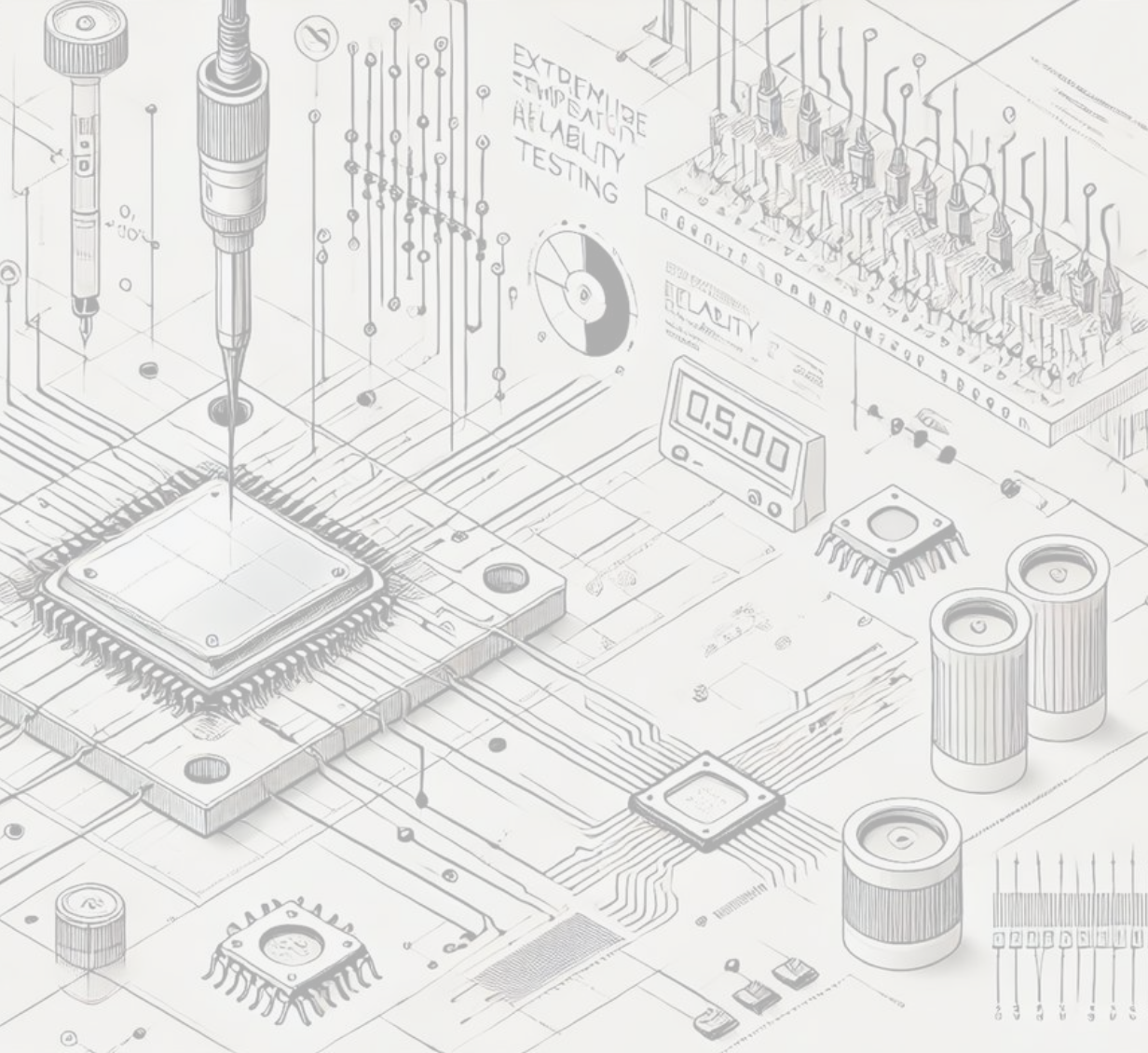
300 x 300



設備用於龍頭
客戶先進封裝
製程前景

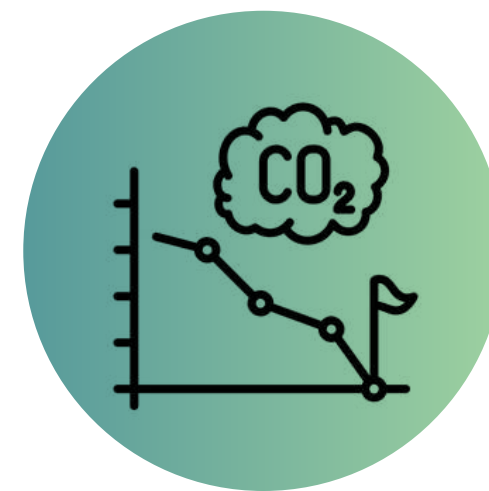
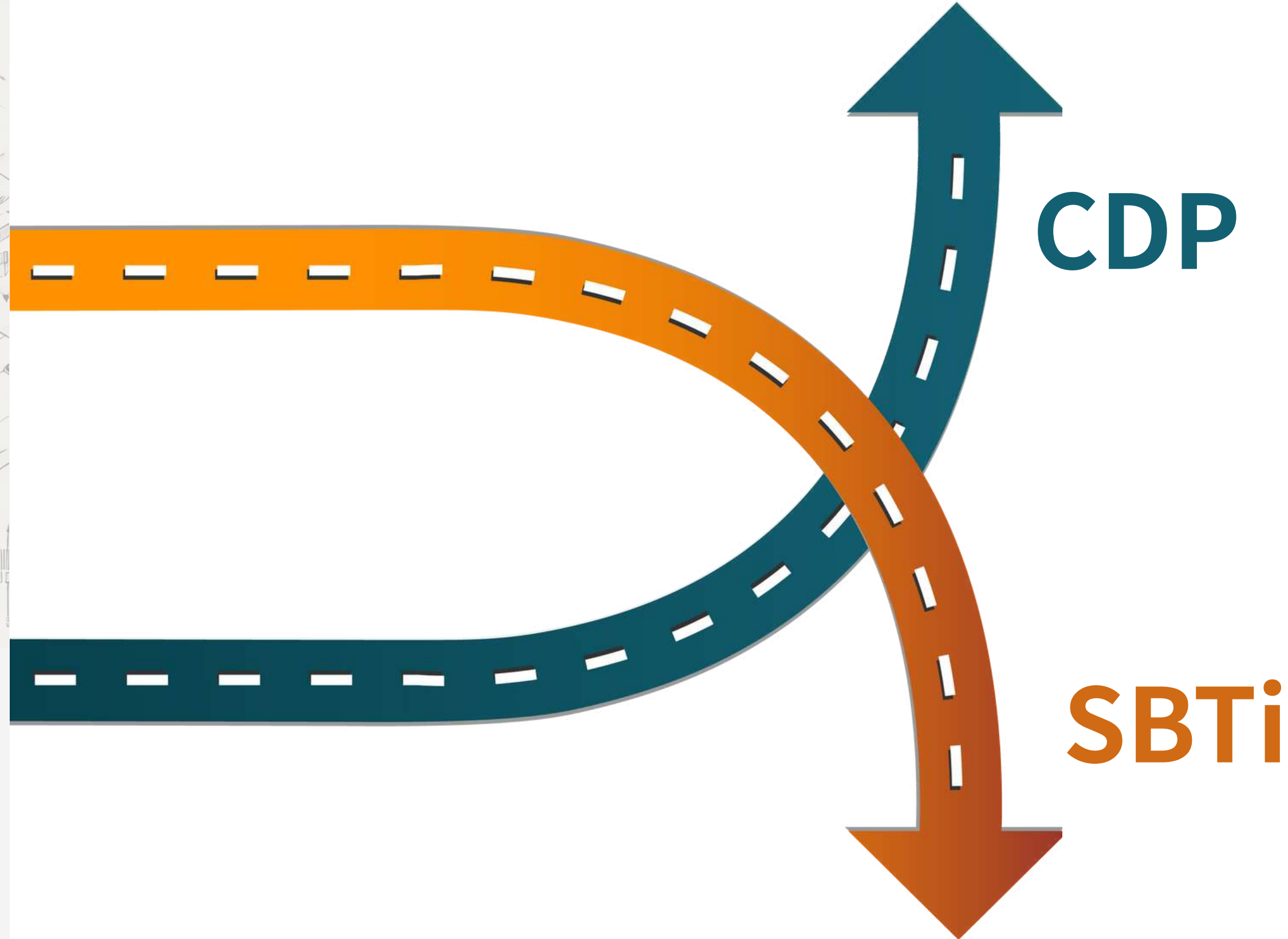
Internationalization (Grand Voyage)





我們對永續 的承諾

設定 ISO 14067
認證目標



*c sun*志聖 Exhibition Preview

touch
TAIWAN 系列展
台北南港展覽館一館四樓

04/16-18, 2025

10:00~17:00

智慧顯示展 | 智慧製造展 | 電子生產製造設備展

敬邀您蒞臨攤位洽詢

4FM719

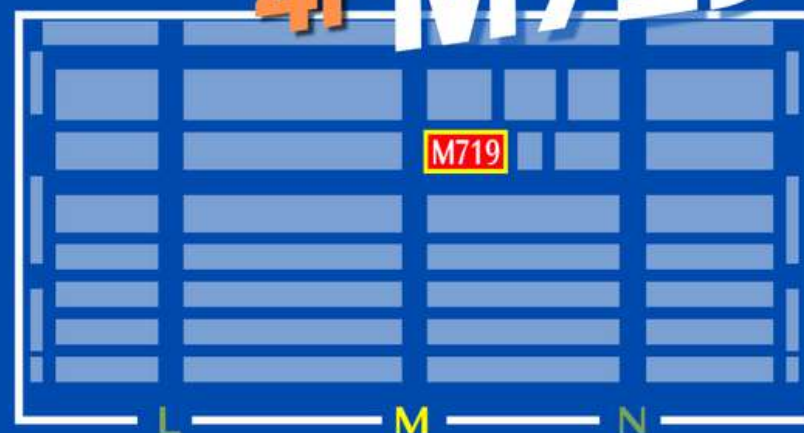
各界產業先進 您好

感謝您一直以來的鼓勵與愛護，

您的信賴與支持是我們成長茁壯的原動力。

誠摯地邀請您蒞臨4FM719攤位，

洽詢全方位智能化解決方案。



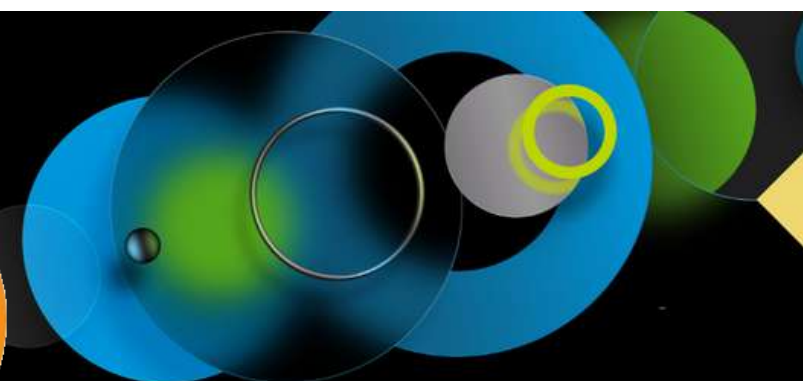
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T STRATEGY ALLIANCE

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GPM 均豪精密

GMM 均華精密

SEMICON[®] 30 YEARS
SOUTHEAST ASIA Special Edition
MAY 20-22, 2025 10:00~17:00 SGT
SANDS EXPO & CONVENTION CENTRE
SINGAPORE



BASEMENT 2
B1524

We sincerely invite you to visit our exhibition booth for inquiries.

Our team will be there to introduce our comprehensive smart solutions, aiming to enhance production line efficiency and create business opportunities.

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GPM 均豪

GMM 均華



The background is a detailed technical illustration in a light orange/red hue. It features various electronic components and tools: a circuit board with multiple integrated circuits, capacitors, and connectors; a digital multimeter displaying '0.5.00'; a CD-ROM; a soldering iron; and several test probes. The text 'EXTREME TEMPERATURE RELIABILITY TESTING' is visible in the upper right. The overall theme is electronics and reliability testing.

Csun

A **G2C+** Alliance Company

Thank you for your attention
